

**In the Drawings:**

**Please replace Figures 1 and 2 with amended Figures 1 and 2 attached hereto.  
Clean copies of amended Figures 1 and 2 are also attached.**

**In the Claims:**

**Please enter the following amended claims 1, 9, 11, 17, 25 and 27:**

1. (Once Amended) A structure comprising:

A) a first conductor;

a first isolation layer situated over said first conductor;

a second conductor situated over said first isolation layer, said second conductor

comprising under bump metal, said second conductor having at least one external pad,

wherein said second conductor is connected to said first conductor;

a second isolation layer situated over said second conductor, said second isolation layer having at least one hole over said at least one external pad of said second conductor;

a bump attach site located at said at least one hole over said at least one external pad.

A~ 9. (Once Amended) The structure of claim 1 wherein said second conductor is patterned from a layer of under bump metal.

113 11. (Once Amended) The structure of claim 10 wherein said second conductor is between approximately 2.0 microns and approximately 5.0 microns thick.

17. (Once Amended) A method for realizing passives, said method comprising steps of:

114 fabricating a first conductor;  
forming a first isolation layer over said first conductor;  
fabricating a second conductor over said first isolation layer, said second conductor comprising under bump metal, said second conductor having at least one external pad, wherein said second conductor is connected to said first conductor;  
forming a second isolation layer over said second conductor, said second isolation layer having at least one hole over said at least one external pad of said second conductor;  
fabricating a bump attach site at said at least one hole over said at least one external pad.

115 25. (Once Amended) The method of claim 17 wherein said second conductor is patterned from a layer of under bump metal.

116 27. (Once Amended) The method of claim 26 wherein said second conductor is between approximately 2.0 microns and approximately 5.0 microns thick.